

# SSW7N60B / SSI7N60B

#### **600V N-Channel MOSFET**

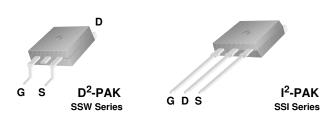
## **General Description**

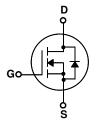
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

#### **Features**

- 7.0A, 600V,  $R_{DS(on)} = 1.2\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 38 nC)
- Low Crss (typical 23 pF)
- Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability





# **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		SSW7N60B / SSI7N60B	Units
V <sub>DSS</sub>	Drain-Source Voltage		600	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		7.0	Α
	- Continuous (T <sub>C</sub> = 100°C)		4.4	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	28	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	420	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	7.0	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	14.7	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		3.13	W
	Power Dissipation (T <sub>C</sub> = 25°C)		147	W
	- Derate above 25°C		1.18	W/°C
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

## **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.85	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	S	Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced	to 25°C		0.65		V/°C
I <sub>DSS</sub>	Zero Oeda Valla da Busia Oemand	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V				10	μΑ
Zero Gate Voltage Drain Current	V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C	)			100	μΑ	
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.5 A			1.0	1.2	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 3.5 A	(Note 4)		8.2		S
<b>Dynam</b>	ic Characteristics Input Capacitance	I			1380	1800	pF
Coss	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			115	150	рF
C <sub>rss</sub>	Reverse Transfer Capacitance				23	30	рF
-155	Tieveree Transier Capabitance					00	Ρ.
Switchi	ing Characteristics			1			
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300 \text{ V}, I_D = 7.0 \text{ A},$			30	70	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$			80	170	ns
$t_{d(off)}$	Turn-Off Delay Time	u u			125	260	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4, 5)		85	180	ns
Qg	Total Gate Charge	$V_{DS} = 480 \text{ V}, I_{D} = 7.0 \text{ A},$			38	50	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10 V			6.4	-	nC
$Q_{gd}$	Gate-Drain Charge		(Note 4, 5)		15		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Rating	s				
I <sub>S</sub>	Maximum Continuous Drain-Source Did					7.0	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	orward Current				28	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 7.0 \text{ A}$				1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 7.0 \text{ A},$			415		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)			4.6		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 15.7mH, I<sub>AS</sub> = 7.0A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  7.0A, di/dt  $\leq$  300A/µs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

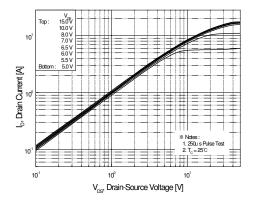


Figure 1. On-Region Characteristics

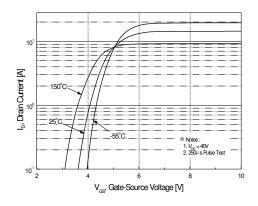


Figure 2. Transfer Characteristics

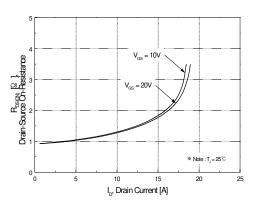


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

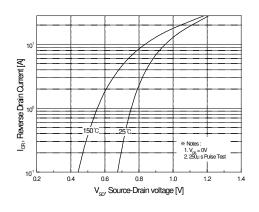


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

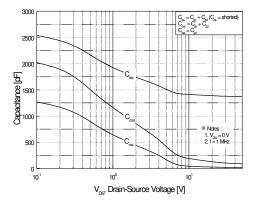


Figure 5. Capacitance Characteristics

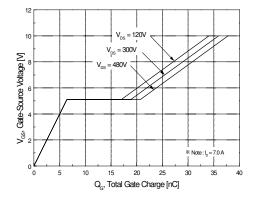


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)

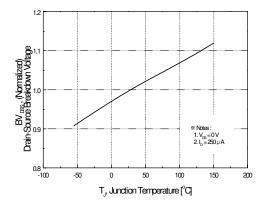
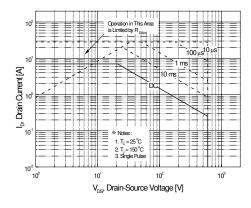


Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



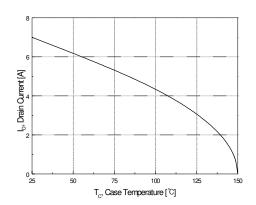


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

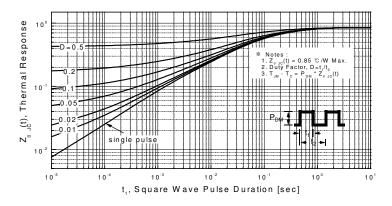
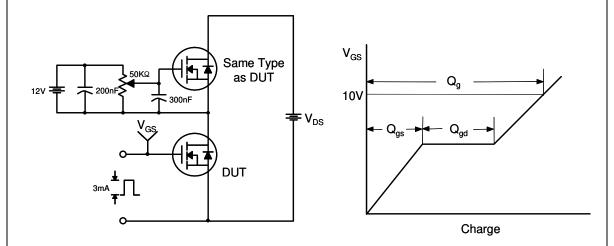


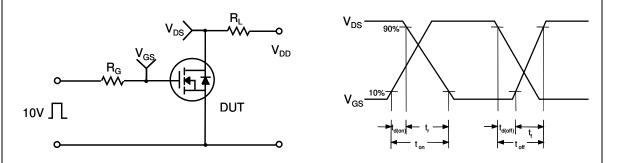
Figure 11. Transient Thermal Response Curve

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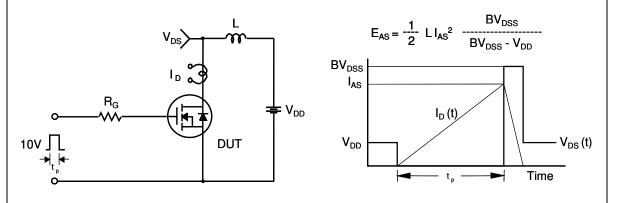
# **Gate Charge Test Circuit & Waveform**



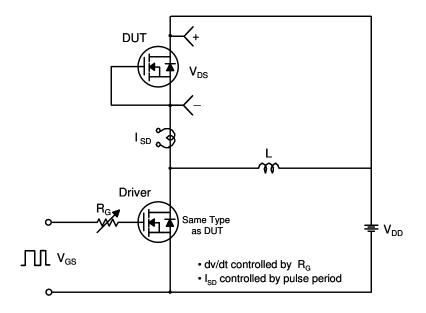
## **Resistive Switching Test Circuit & Waveforms**

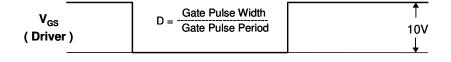


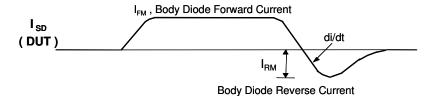
## **Unclamped Inductive Switching Test Circuit & Waveforms**

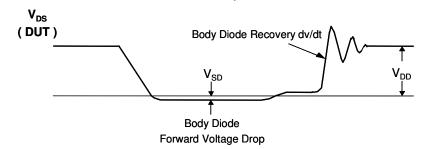


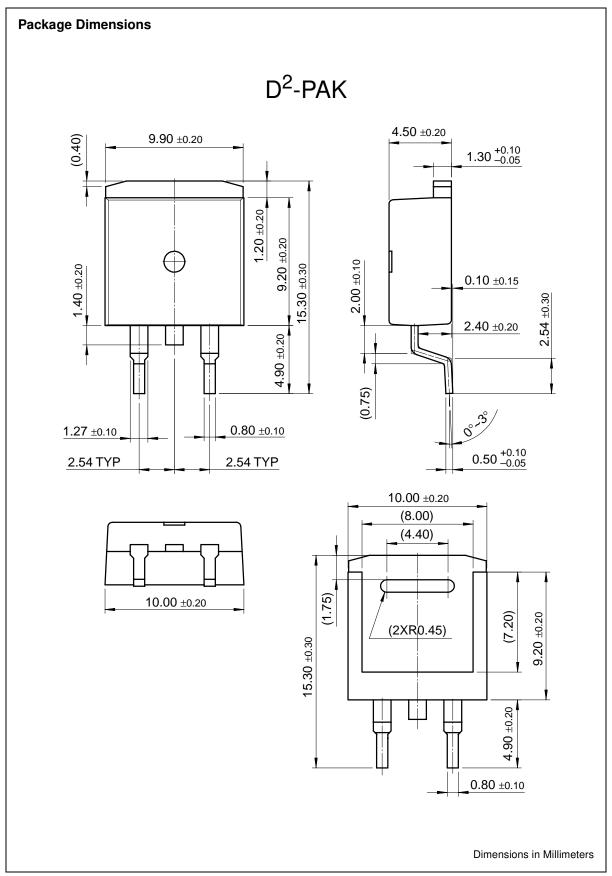
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

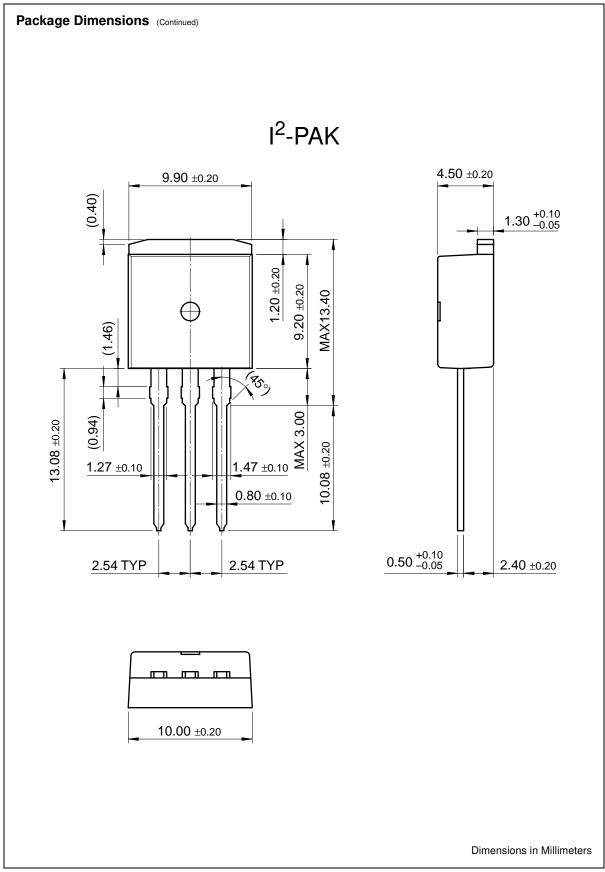












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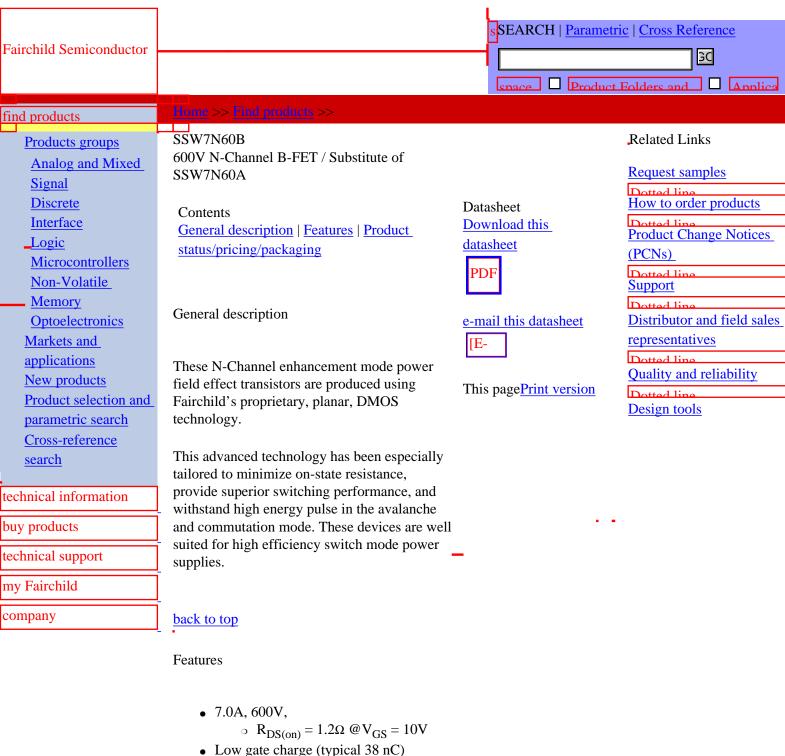
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- Low Crss (typical 23 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method

Product Folder - Fairchild P/N SSW7N60B - 600V N-Channel B-FET / Substitute of SSW7N60A

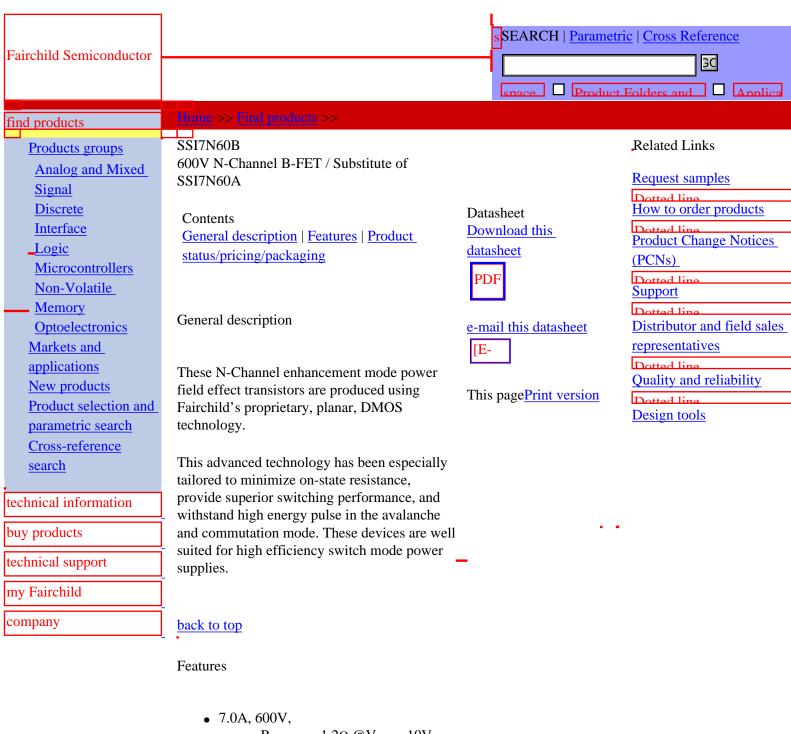
SSW7N60BTM	Full Production	\$1.00	TO-263(D2PAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

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Product Folder - Fairchild P/N SSI7N60B - 600V N-Channel B-FET / Substitute of SSI7N60A

SSI7N60BTU	Full Production	\$1.00	TO-262(I2PAK)	3	RAIL

<sup>\* 1,000</sup> piece Budgetary Pricing

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